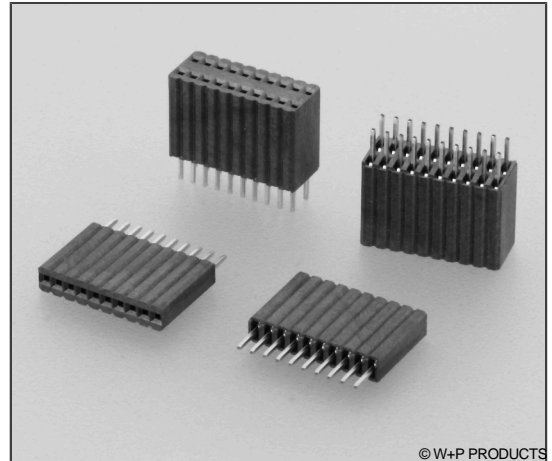


46-710 Economy Version

Buchsenleisten RM 1,27x2,54mm, gerade, 1-/2-reihig - Bauhöhe 8,50mm
 Female Headers, 1.27x2.54mm Pitch, Straight, Single/Double Row – 8.5mm Profile

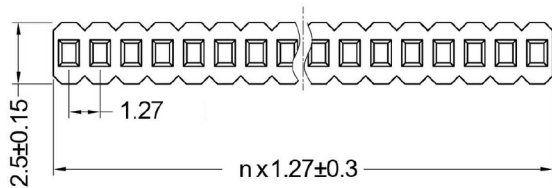
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Phosphorbronze <i>Phosphor bronze</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC/DC
Nennstrom <i>Current Rating</i>	1 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ~ +105 °C
Verarbeitung <i>Processing</i>	260 °C für 10 sec. / 230 °C für 30-60 sec. 260 °C for 10 sec. / 230 °C for 30-60 sec.

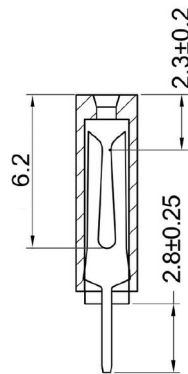
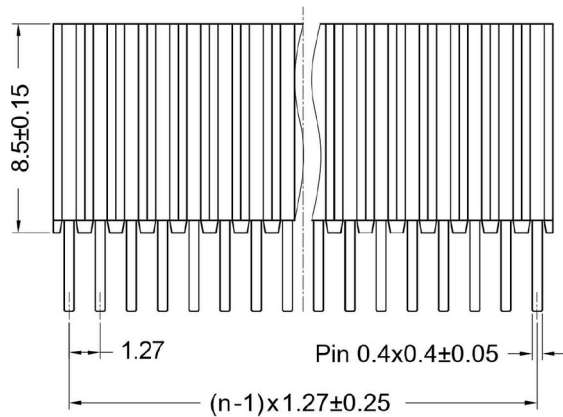
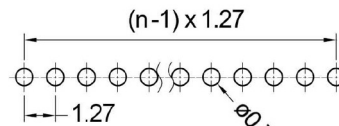


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Geeignet für 0,46mm Vierkantstifte
 Mates with 0.46mm square pins



Recommended PCB Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)



Series

46-710

Contacts*

015

003-040 Einreihig
 Single row

Rows

1

1 Einreihig
 Single row

Plating

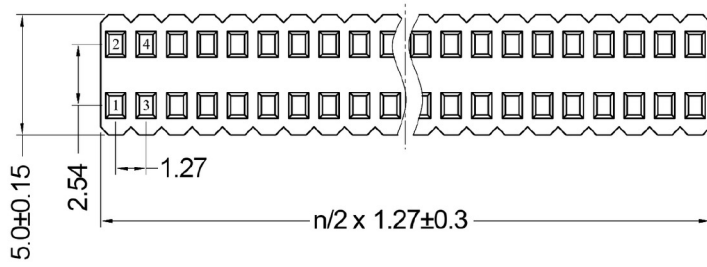
00

00 Vergoldet
 Gold plated

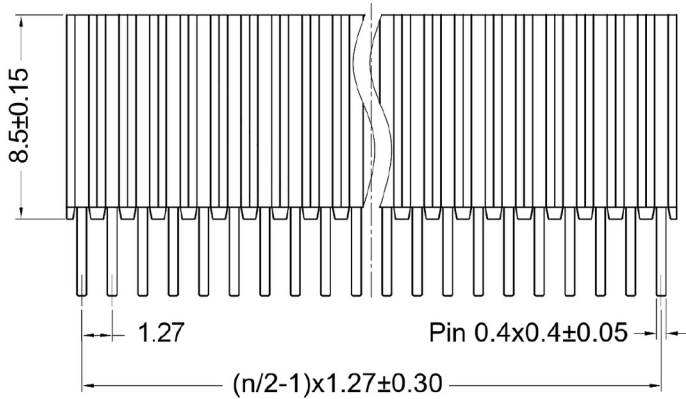
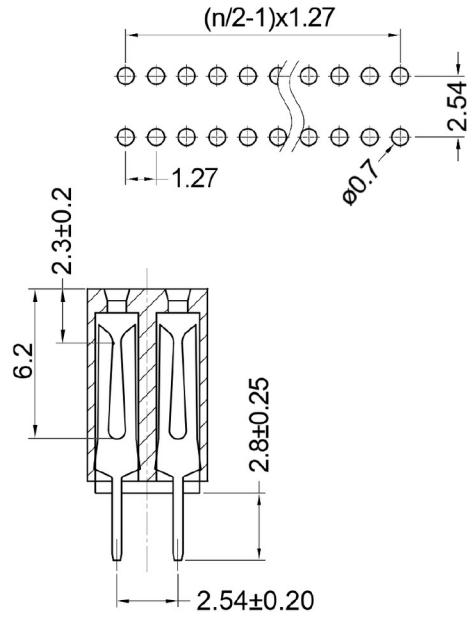
46-710 Economy Version

Buchsenleisten RM 1,27x2,54mm, gerade, 1-/2-reihig - Bauhöhe 8,50mm

Female Headers, 1.27x2.54mm Pitch, Straight, Single/Double Row – 8.5mm Profile



Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series

46-710

Contacts*

040

006-100 Zweireihig
Double row

Rows

2

2 Zweireihig
Double row

Plating

00

00 Vergoldet
Gold plated

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

